

WHAT WE CLAIM IS:

1. A semiconductor device comprising:
 - a substrate;
 - 5 a semiconductor chip having one surface bonded to a surface of the substrate; and
 - a warp preventing sheet bonded to the other surface of the semiconductor chip.
- 10 2. A semiconductor device according to Claim 1, wherein the warp preventing sheet has a coefficient of elasticity substantially equal to that of the substrate.
- 15 3. A semiconductor device according to Claim 1, wherein the warp preventing sheet has a coefficient of thermal expansion substantially equal to that of the substrate.
- 20 4. A semiconductor device according to Claim 1, wherein a base of the warp preventing sheet is made of material identical with that of a base of the substrate.
5. A semiconductor device according to Claim 1, wherein a base of each of the substrate and the warp preventing sheet is a polyimide resin.

6. A semiconductor device according to Claim 1, wherein the warp preventing sheet has a thickness substantially equal to that of the substrate.

5 7. A semiconductor device according to Claim 1, wherein
the semiconductor device is a thin semiconductor device of a
chip-size package type.